

+5V-Powered, Multichannel RS-232 Drivers / Receivers

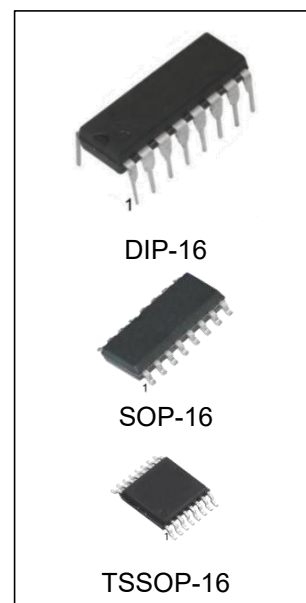
General Description

SP232E is purposed for application in high-performance information processing systems and control devices of wide application.

Input voltage levels are compatible with standard CMOS levels.

Features

- Output voltage levels are compatible with input levels of K-MOS, N-MOS and TTL integrated circuits.
- Supply voltage : 5V
- Low input current: 1.0 μ A; 0.1 μ A at Ta= 25 °C.
- Output current 24 mA.
- Latching current not less than 450 mA at Ta= 25°C
- The transmitter outputs and receiver inputs are protected to ± 15 kV Air ESD.



Ordering Information

DEVICE	Package Type	MARKING	Packing	Packing Qty
SP232EIN	DIP-16	SP232EI,232EI	TUBE	1000pcs/Box
SP232EIM/TR	SOP-16	SP232EI,232EI	REEL	2500pcs/Reel
SP232EIMT/TR	TSSOP-16	SP232EI,232EI	REEL	2500pcs/Reel
SP232ECN	DIP-16	SP232EC,232EC	TUBE	1000pcs/Box
SP232ECM/TR	SOP-16	SP232EC,232EC	REEL	2500pcs/Reel
SP232ECMT/TR	TSSOP-16	SP232EC,232EC	REEL	2500pcs/Reel

Pin symbols in package

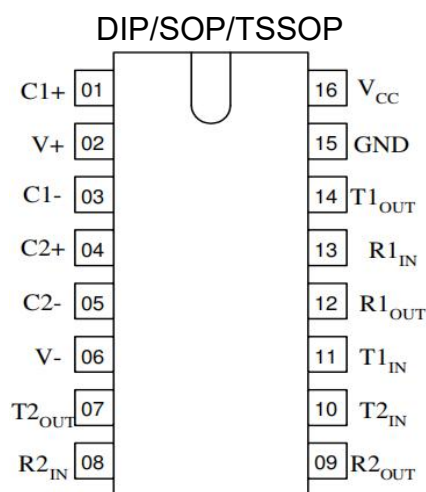


Table of pin description

Pin No.	Symbol	Pin name
01	C1+	Output of external capacitance of positive voltage multiplier unit
02	V+	Output of positive voltage of multiplier unit
03	C1-	Output of external capacitance of positive voltage multiplier unit
04	C2+	Output of external capacitance of negative voltage multiplier unit
05	C2-	Output of external capacitance of negative voltage multiplier unit
06	V-	Output of negative voltage of multiplier unit
07	T2 _{OUT}	Output of transmitter data (levels RS – 232)
08	R2 _{IN}	Input of receiver data (levels RS – 232)
09	R2 _{OUT}	Output of receiver data (levels TTL/KMOS)
10	T2 _{IN}	Input of transmitter data (levels TTL/KMOS)
11	T1 _{IN}	Input of transmitter data (levels TTL/KMOS)
12	R1 _{OUT}	Output of receiver data (levels TTL/KMOS)
13	R1 _{IN}	Input of receiver data (levels RS – 232)
14	T1 _{OUT}	Output of transmitter data (levels RS – 232)
15	GND	Common output
16	V _{CC}	Supply output of voltage source

Truth table

Inputs	Outputs
R_{IN}, T_{IN}	R_{OVT}, T_{OVT}
H	L
L	H
Note - H – voltage high level; L – low voltage level	

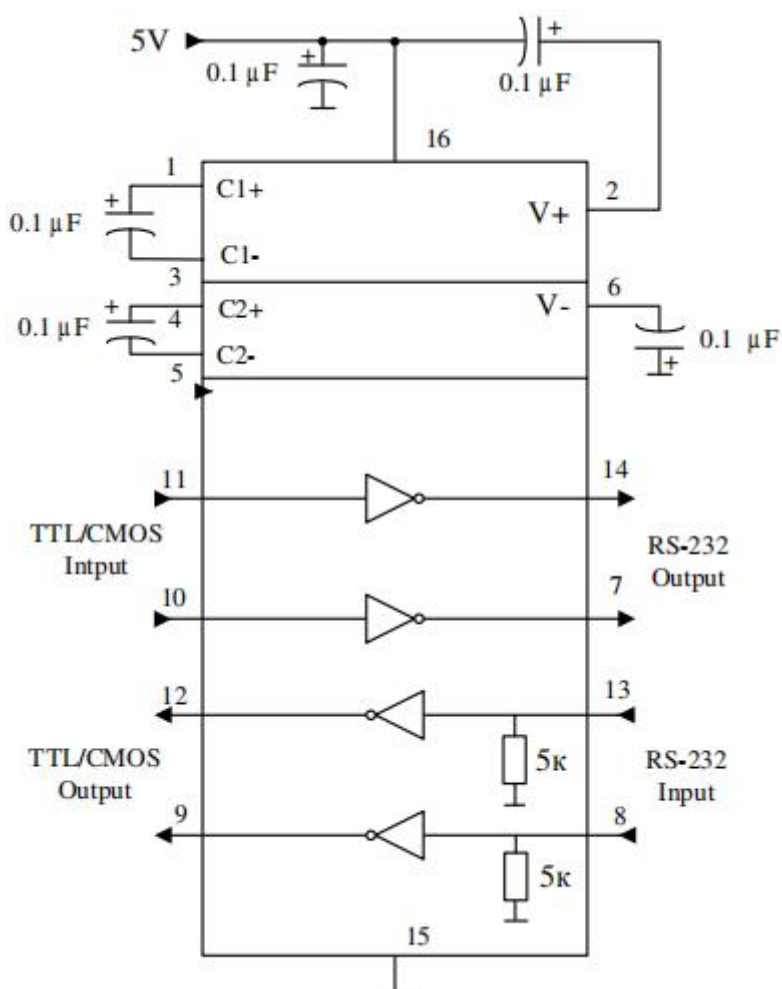
Maximum conditions

Symbol	Parameter	Rate		Unit
		min	max	
V_{CC}	Supply voltage	-0.3	6.0	V
$V+$	Transmitter high output voltage	$V_{CC} - 0.3$	14	
$V-$	Transmitter low output voltage	-0.3	-14	
V_{TIN}	Transmitter input voltage	-0.3	$V+ + 0.3$	
V_{RIN}	Receiver input voltage	-30	30	
P_D	Dissipated power	-	842	mW
	DIP – package			
	SOP - package		762	
I_{SC}	Output current of transmitter short circuit	-	Continuously	mA
T_a	Ambient temperature	-60	150	°C
T_L	Lead Temperature (Soldering, 10 seconds)	-	260	°C

Note: Absolute Maximum Ratings indicate limits beyond which damage to the device may occur. Operating Ratings indicate conditions for which the device is intended to be functional, but specific performance is not ensured.

Recommended Operating Conditions

Symbol	Parameter		Rate		Unit
			min	max	
V _{CC}	Supply voltage		4.5	5.5	V
V+	Transmitter output high voltage		5.0	-	
V-	Transmitter output low voltage		-5.0	-	
V _{TIN}	Transmitter input voltage		0	V _{CC}	
V _{RIN}	Receiver input voltage		-30	30	
I _{SC}	Transmitter short circuit output current		-	±60	mA
Ta	Ambient temperature	SP232EC	0	70	°C
		SP232EI	-40	85	°C



Static parameters

Symbol	Parameter	Test conditions	Rate				Unit
			25℃		-40 ℃ to 85 ℃		
			min	max	min	max	
I _{CC}	Consumption current static	V _{CC} =5.0V V _{IL} = 0V	-	10.0	-	14.0	mA
Receiver electrical parameters							
V _h	Hysteresis voltage	V _{CC} =5.0V	0.2	0.9	0.2	1.0	V
V _{On}	On (operation) voltage	V _O ≤ 0.1 V I _{OL} ≤ 20 uA	-	2.4	-	2.3	
V _{off}	Off (dropout) voltage	V _O ≥ V _{CC} -0.1V I _{OH} ≤ -20 uA	0.8	-	0.9	-	
V _{OL}	Output low voltage	I _{OL} = 3.2 mA V _{CC} = 4.5 V V _{IH} = 2.4 V	-	0.3	-	0.4	
V _{OH}	Output high voltage	I _{OH} = -1.0 mA V _{CC} = 4.5 V V _{IL} = 0.8 V	3.6	-	3.5	-	
R _i	Input resistance	V _{CC} = 5.0 V	3.0	7.0	3.0	7.0	kOhm
Transmitter electrical parameters							
V _{OL}	Output low voltage	V _{CC} = 4.5 V V _{IH} = 2.0 V R _L = 3.0 kOhm	-	-5.2	-	-5.0	V
V _{OH}	Output high voltage	V _{CC} = 4.5 V V _{IL} = 0.8 V R _L = 3.0 kOhm	5.2	-	5.0	-	
I _{IL}	Input low current	V _{CC} =5.5 V V _{IL} = 0 V	-	-1.0	-	-10.0	uA
I _{IH}	Input high current	V _{CC} =5.5 V V _{IH} = V _{CC}		1.0		10.0	
SR	Speed of output front change	V _{CC} =5.0 V C _L =50 - 1000 pF R _L = 3.0 - 7.0 kOhm	3.0	30	2.7	27	V/μs
R _O	Output resistance	V _{CC} = V ₊ = V ₋ = 0 V V _O = ± 2 V	350	-	300	-	Ohm
I _{sc}	Short circuit output current	V _{CC} =5.5 V V _O = 0 V V _I = V _{CC} V _I = 0 V		-50 50		-60 60	mA
ST	Speed of information transmission	V _{CC} =4.5 V C _L = 1000 pF R _L = 3.0 kOhm t _W = 7us (for extreme -t _W = 8us)	140	-	120	-	

Dynamic parameters

Symbol	Parameter	Test conditions	Rate				Unit
			25°C		from -40°C to 85°C		
			min	max	min	max	
tPHLR (tPLHR)	Signal propagation delay time when switching on (off)	V _{CC} = 4.5 V C _L = 150 pF V _{IL} = 0 V V _{IH} = 3.0 V t _{LH} = t _{HL} ≤ 10 ns	-	9.7	-	10	us
tphlt (tPLHT)	Signal propagation delay time when switching on (off)	V _{CC} = 4.5 V C _L = 2500 pF V _{IL} = 0 V V _{IH} = 3.0 V R _L = 3 kOhm t _{LH} = t _{HL} ≤ 10 ns		5.0*		6.0*	

Capacitance

Symbol	Parameter	V _{CC}	Rate	Unit
C _{IN}	Input capacitance	5.0	9.0	pF
CPD	Dynamic capacitance		90	

Timing diagram when measuring IC dynamic parameters

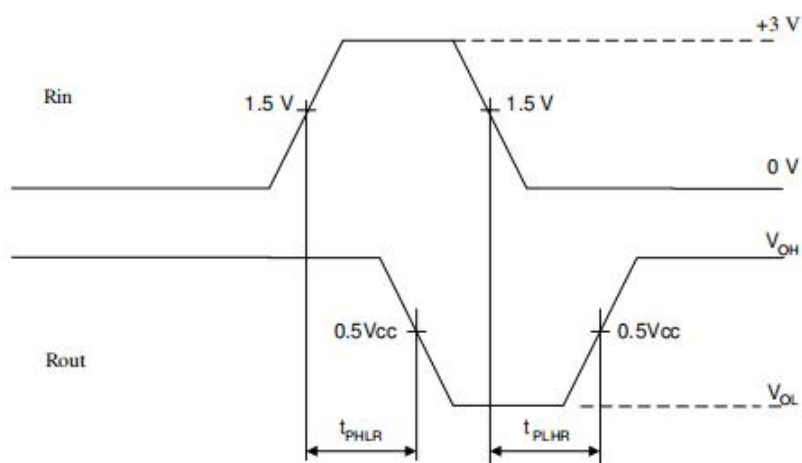


Figure 3

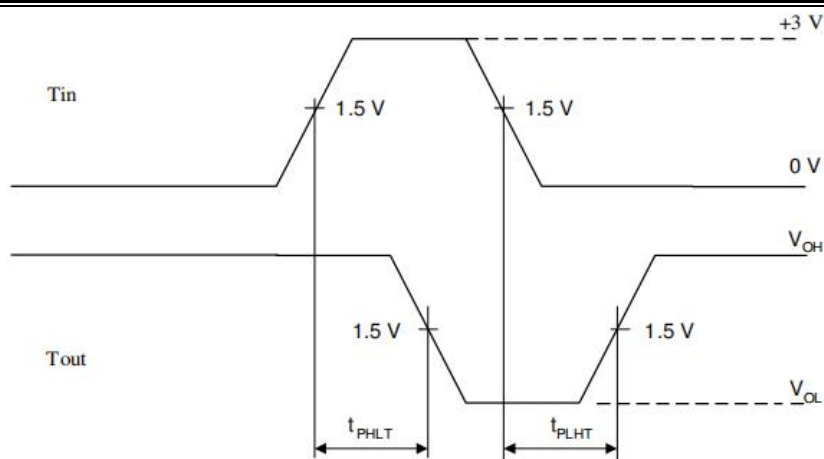


Figure 4

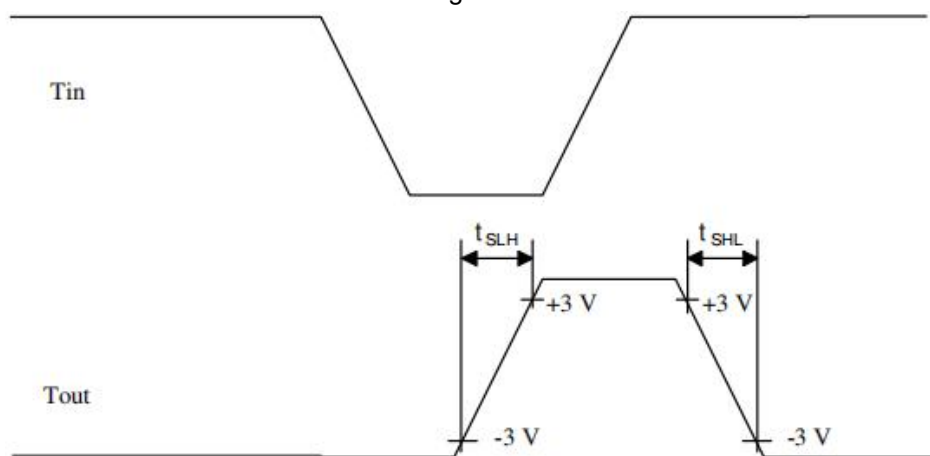


Figure 5

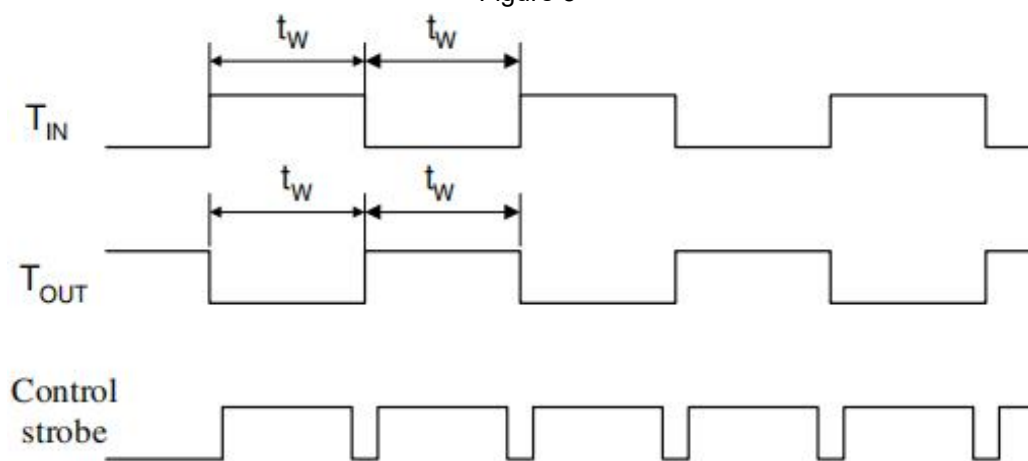
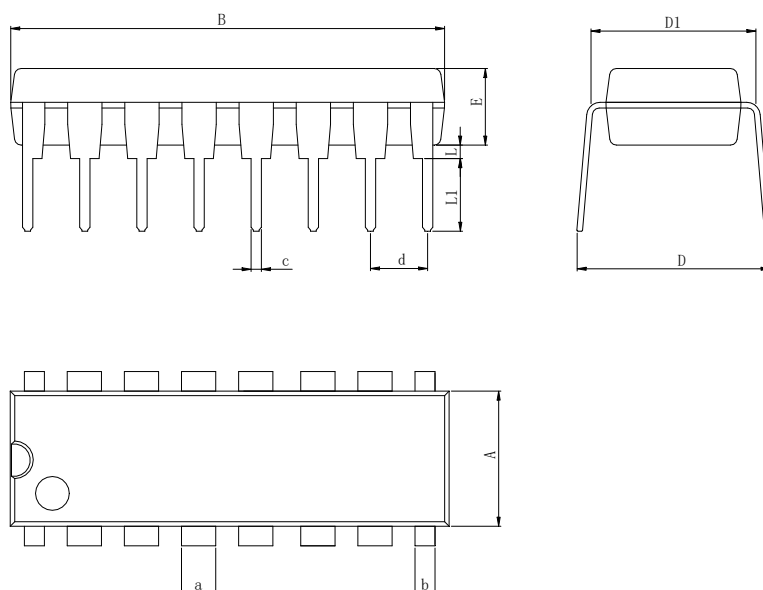


Figure 6

Physical Dimensions

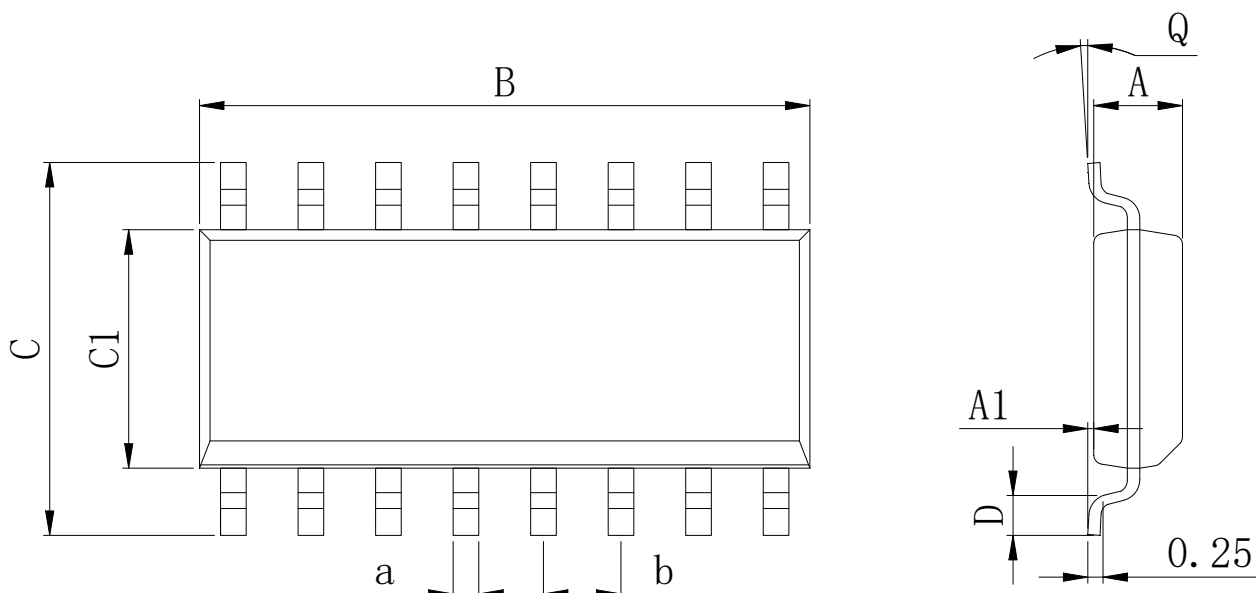
DIP-16



Dimensions In Millimeters(DIP-16)

Symbol:	A	B	D	D1	E	L	L1	a	b	c	d
Min:	6.10	18.94	8.10	7.42	3.10	0.50	3.00	1.50	0.85	0.40	2.54 BSC
Max:	6.68	19.56	10.9	7.82	3.55	0.70	3.60	1.55	0.90	0.50	

SOP-16

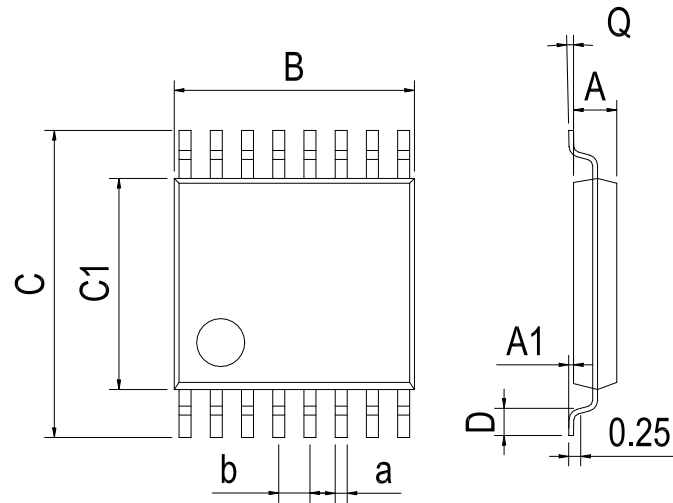


Dimensions In Millimeters(SOP-16)

Symbol:	A	A1	B	C	C1	D	Q	a	b
Min:	1.35	0.05	9.80	5.80	3.80	0.40	0°	0.35	1.27 BSC
Max:	1.55	0.20	10.0	6.20	4.00	0.80	8°	0.45	

Physical Dimensions

TSSOP-16



Dimensions In Millimeters(TSSOP-16)									
Symbol:	A	A1	B	C	C1	D	Q	a	b
Min:	0.85	0.05	4.90	6.20	4.30	0.40	0°	0.20	0.65 BSC
Max:	0.95	0.20	5.10	6.60	4.50	0.80	8°	0.25	

Revision History

DATE	REVISION	PAGE
2018-8-12	New	1-11
2023-9-14	Modify the package dimension diagram TSSOP-16 、 Update encapsulation typeUpdated DIP-16 dimension	1、 8、 9
2024-11-6	Add a model marking name、 Update Lead Temperature、	1、 3

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